



SOT1832-1

plastic thermal enhanced ultra thin quad flat package; no leads; 16 terminals; body 2.4 x 1.6 x 0.5 mm

26 April 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HUQFN16
Package type industry code	HUQFN16
Package style descriptive code	HUQFN (thermal enhanced ultra thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-4-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.55	-	1.6	1.65	mm
E	package width	2.35	-	2.4	2.45	mm
A	seated height	0.45	-	0.5	0.55	mm
A ₂	package height	-	-	0.1	-	mm
e	nominal pitch	-	-	-	-	
n ₂	actual quantity of termination	-	-	16	-	

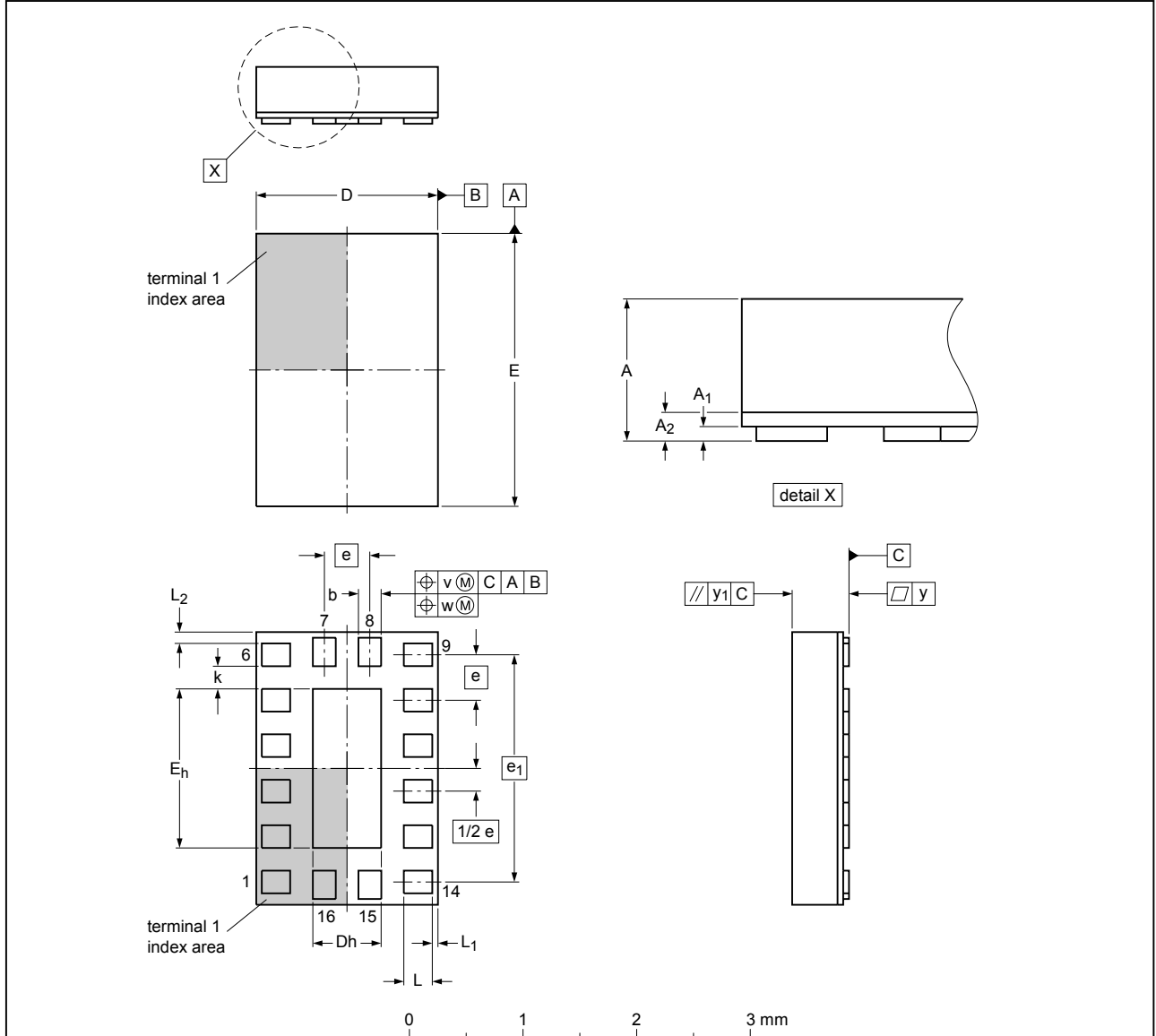


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2. Package outline

HUQFN16: plastic thermal enhanced Ultra thin quad flat package; no leads; 16 terminals; body 2.4 x 1.6 x 0.5 mm

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Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	D _h	E	E _h	e	e ₁	k	L	L ₁	L ₂	v	w	y	y ₁
max	0.55	0.05		0.25	1.65	0.65	2.45	1.45			0.25	0.30	0.10	0.15				
mm nom	0.50	0.03	0.10	0.20	1.60	0.60	2.40	1.40	0.4	2.0	0.20	0.25	0.05	0.10	0.1	0.05	0.05	0.1
min	0.45	0.00		0.15	1.55	0.55	2.35	1.35			0.15	0.20	0.01	0.05				

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1832-1	---	---	---		-16-01-21- 16-02-15

Fig. 1. Package outline HUQFN16 (SOT1832-1)

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3. Soldering

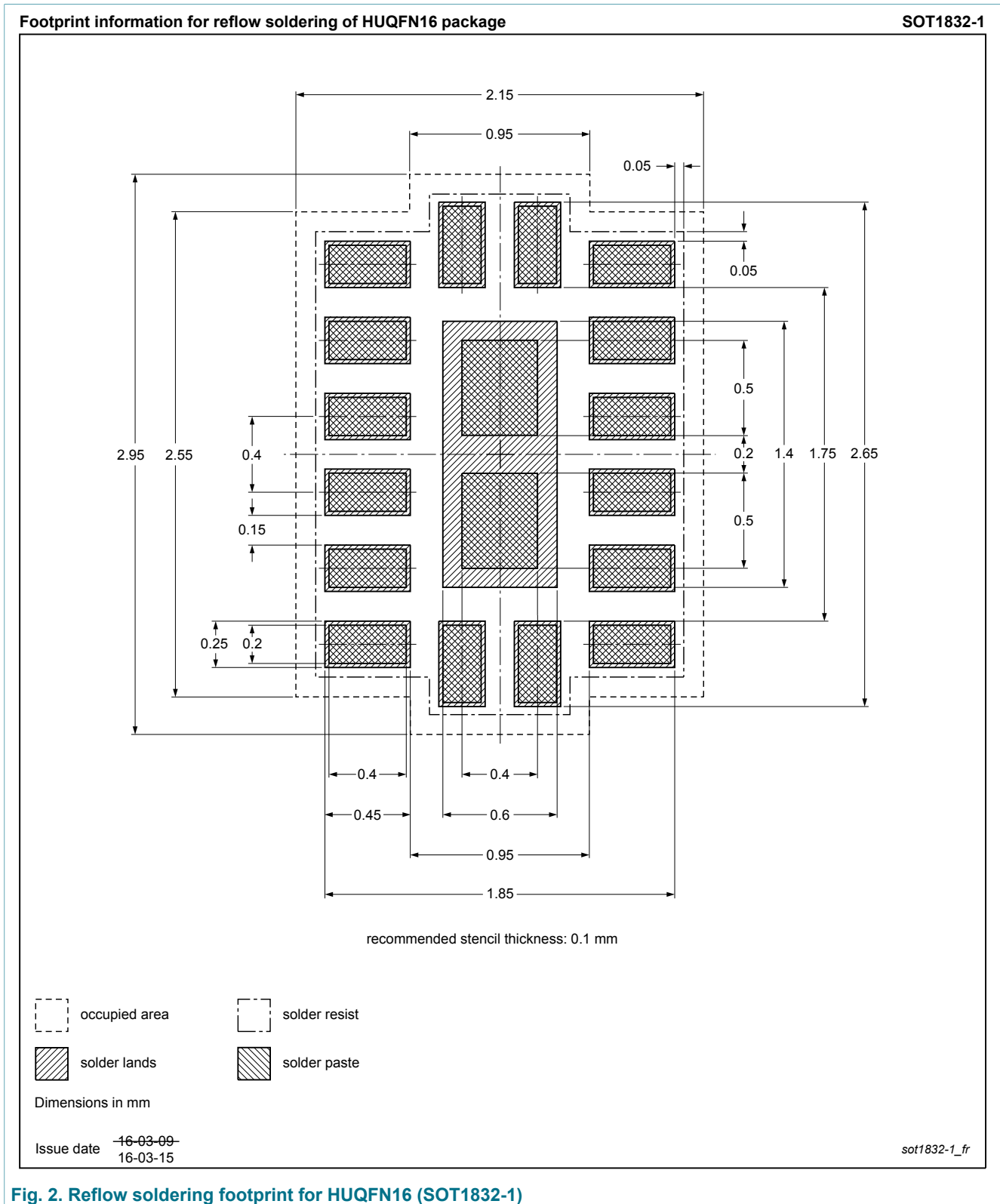


Fig. 2. Reflow soldering footprint for HUQFN16 (SOT1832-1)

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4. Legal information

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